

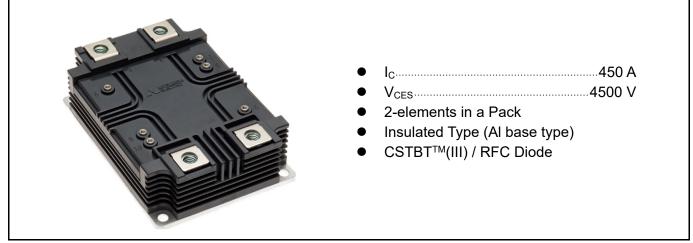
< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM450DE-90X

HIGH POWER SWITCHING USE INSULATED TYPE

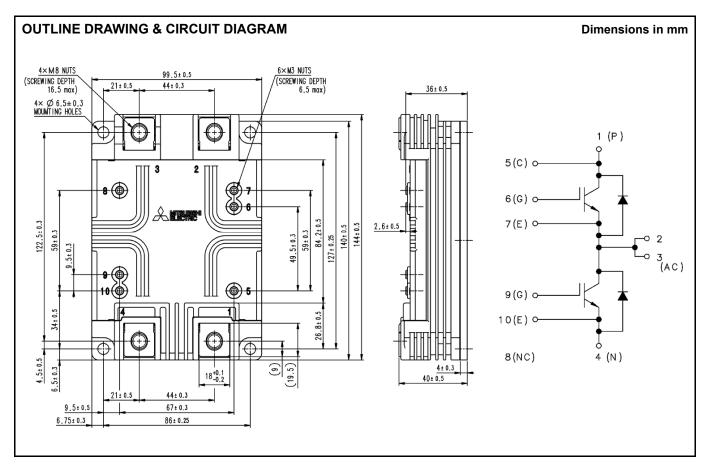
5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

CM450DE-90X



APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers



< High Voltage Insulated Gate Bipolar Transistor: HVIGBT > CM450DE-90X HIGH POWER SWITCHING USE INSULATED TYPE 5th-Version HVIGBT (High

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MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
VCES	Collector omitter voltage	V _{GE} = 0 V, T _j = -40+150 °C	4500	v
	Collector-emitter voltage	V _{GE} = 0 V, T _j = −50 °C	4400	v
VGES	Gate-emitter voltage	V _{CE} = 0 V, T _j = 25 °C	±20	V
lc	Callester sumert	DC, T _c = 100 °C	450	
ICRM	Collector current	Pulse (Note 1)	900	A
le	Fue the second (Note 2)	DC, Tc = 75 °C	450	
I _{ERM}	Emitter current (Note 2)	Pulse (Note 1)	900	A
Ptot	Maximum power dissipation (Note 3)	T₀ = 25°C, IGBT part	4800	W
Viso	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min. T _c = 25 °C	10200	V
Q _{PD}	Partial discharge	Charged part to the baseplate V1 = 6900 Vrms, V2 = 5100 Vrms AC 60 Hz, T_c = 25 °C (acc. to IEC 61287)		рС
Tj	Junction temperature —		-50 ~ +150	°C
T _{stg}	Storage temperature	—	-55 ~ +150	°C
Tjop	Operating junction temperature	—	-50 ~ +150	°C
t _{psc}	Short circuit pulse width	$ \begin{array}{l} V_{CC} \leq 3400 \; \text{V}, \; L_{S} = 100 \; \text{nH}, \; T_{j} = T_{jop} \\ V_{GE} = \pm 15 \; \text{V}, \; R_{G(on)} = 6.8 \; \Omega, \; R_{G(off)} = 100 \; \Omega \end{array} $	10	μs

ELECTRICAL CHARACTERISTICS

Question	Item	Conditions			1.1		
Symbol				Min.	Тур.	Max.	Unit
			T _j = 25 °C	I	_	2.0	
ICES	Collector cutoff current	V _{CE} = V _{CES} V _{GE} = 0 V	T _j = 125 °C		—	—	mA
		VGE – U V	T _j = 150 °C		_	18.0	
V _{GE(th)}	Gate-emitter threshold voltage	V _{CE} = 10 V, I _C = 45 mA, T _j =	25 °C	6.5	7.0	7.5	V
Iges	Gate leakage current	V _{GE} = V _{GES} , V _{CE} = 0 V, T _j = 25 °C				0.5	μA
		Ic = 450 A (Note 4)	T _j = 25 °C	_	2.60		
V _{CEsat}	Collector-emitter saturation voltage	$V_{GE} = 15 V$	T _j = 125 °C		3.30		V
		VGE - 15 V	T _j = 150 °C		3.50	4.00	
Cies	Input capacitance			I	50.0	—	
Coes	Output capacitance	V _{CE} = 10 V, V _{GE} = 0 V f = 100 kHz, T _i = 25 °C			3.0	—	nF
Cres	Reverse transfer capacitance	$1 = 100 \text{ kHz}, 1_{j} = 25 \text{ C}$		_	0.4		
Q _G	Total gate charge	V _{CC} = 2800 V, I _C = 450 A V _{GE} = ±15 V, T _i = 25 °C		-	3.3	_	μC
t _{d(on)}	Turn-on delay time		T _j = 150 °C	_		0.80	μs
tr	Rise time	V _{CC} = 2800 V	T _j = 150 °C	_		0.45	μs
E _{on(10%)}	Turn-on switching energy per pulse (Note 5)	I _C = 450 A V _{GE} = ±15 V R _{G(on)} = 6.8 Ω L _s = 100 nH Inductive load	Tj = 25 °C	_	1.80		
			T _j = 125 °C		2.05	—	J
			T _j = 150 °C		2.05	—	
	Turn-on switching energy per pulse		Tj = 25 °C	_	1.80	—	
Eon			T _j = 125 °C		2.10	—	
			T _j = 150 °C	_	2.15	—	
	Turn-off delay time		T _j = 25 °C		5.50		
t _{d(off)}			T _j = 125 °C		5.90		μs
			T _j = 150 °C	_	5.90		
		V _{CC} = 2800 V	T _j = 25 °C				
t _f	Fall time	$I_{C} = 450 \text{ A}$ $V_{GE} = \pm 15 \text{ V}$	T _j = 125 °C		0.40	—	μs
			T _i = 150 °C	_	0.45	—	
Eoff(10%)	Turn-off switching energy per pulse ^(Note 5)	- R _{G(off)} = 100 Ω L _s = 100 nH	T _i = 25 °C	-	1.10	_	
		Ls - 100 IIH	T _j = 125 °C		1.40	—	J
			T _j = 150 °C		1.45	—	
E _{off}	- - - - - - - - - -	1	T _j = 25 °C	_	1.25		
	Turn-off switching energy per pulse		T _j = 125 °C	—	1.60	—	J
			T _i = 150 °C		1.70		1

< High Voltage Insulated Gate Bipolar Transistor: HVIGBT > CM450DE-90X HIGH POWER SWITCHING USE INSULATED TYPE 5th-Version HVIGBT (High)

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

ELECTRICAL CHARACTERISTICS

Symbol	ltem	Conditions		Limits			Unit
Symbol	item			Min.	Тур.	Max.	Unit
			T _j = 25 °C	_	2.50	—	
VEC	Emitter-collector voltage (Note 2)	I _E = 450 A ^(Note 4) V _{GE} = 0 V	Tj = 125 °C	_	3.05		V
		VGE - 0 V	T _j = 150 °C		3.20	3.70	
			T _j = 25 °C		1.80		
trr	Reverse recovery time (Note 2)		T _j = 125 °C		2.10	_	μs
			T _j = 150 °C		2.20	_	
			T _j = 25 °C		400		
Irr	Reverse recovery current (Note 2)		T _j = 125 °C		400		А
			T _j = 150 °C		400		
	Reverse recovery charge (Note 2, 6)	$V_{CC} = 2800 V$ $I_{E} = 450 A$ $V_{GE} = \pm 15 V$ $R_{G(on)} = 6.8 \Omega$ $L_{s} = 100 \text{ nH}$	T _j = 25 °C		500		
Qrr(10%)			T _j = 125 °C	_	670		μC
			T _j = 150 °C	_	710		
	Reverse recovery charge (Note 2)		T _j = 25 °C	_	520	—	
Qrr			T _j = 125 °C	_	720	—	μC
		Inductive load	T _j = 150 °C		770		
		-	T _j = 25 °C		0.80		
Erec(10%)	Reverse recovery energy per pulse (Note 2, 5)		T _j = 125 °C	_	1.15		J
			T _j = 150 °C		1.20		
	Reverse recovery energy per pulse (Note 2)		T _j = 25 °C		0.85		
Erec			T _j = 125 °C		1.30	_	J
			T _j = 150 °C		1.35		

THERMAL CHARACTERISTICS

Symbol	Item	Conditions		Limits		
Symbol Item		Conditions	Min.	Тур.	Max.	Unit
R _{th(j-c)Q}	Thermal resistance	Junction to Case, IGBT part, 1/2 module		_	26.0	K/kW
R _{th(j-c)D}	mermairesistance	Junction to Case, FWDi part, 1/2 module		_	43.0	K/kW
Rth(c-s)	Contact thermal resistance	Case to heat sink, 1/2 module $\lambda_{grease} = 1 \text{ W/m} \cdot \text{k}$, D _(c-s) = 70 µm	—	16.0		K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
		Conditions	Min.	Тур.	Max.	Unit
Mt		Main terminals screw: M8	7.0	—	14.0	N∙m
Ms	Mounting torque	torque Mounting screw: M6		—	6.0	N∙m
Mt		Auxiliary terminals screw: M3	0.4	—	0.8	N∙m
m	Mass	—	_	0.75	_	kg
CTI	Comparative tracking index	—	600	—	_	_
da	Clearance	—	26.0	—	_	mm
ds	Creepage distance	—	56.0	—	—	mm
L _{P(P-N)}	Parasitic stray inductance	—		40.0	_	nH
Rcc'+ee'	Internal lead resistance	$T_c = 25 \text{ °C}, 1/2 \text{ module}$	_	0.59		mΩ

Note 1. Pulse width and repetition rate should be such that junction temperature (T_j) does not exceed maximum T_{jop} rating (150°C).

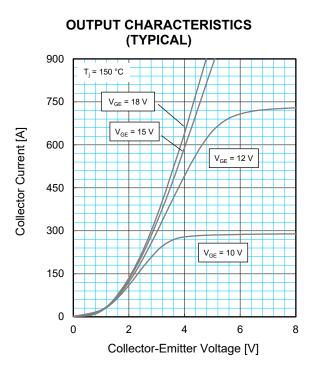
Note 2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWD_i).

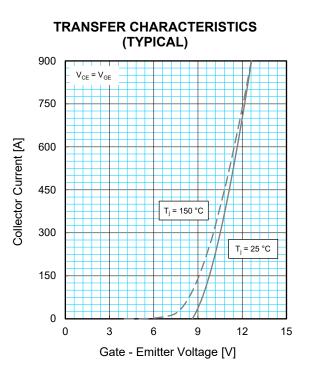
Note 3. Junction temperature (T_j) should not exceed T_{j_max} rating (150°C).

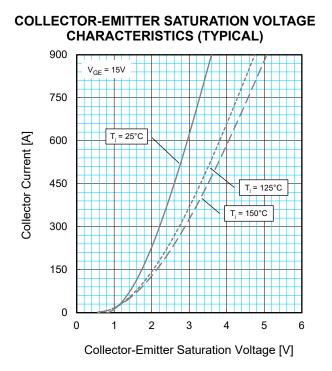
Note 4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

Note 5. The integration range of switching energies is from 10%V_{CE} to 10%I_C(I_E).

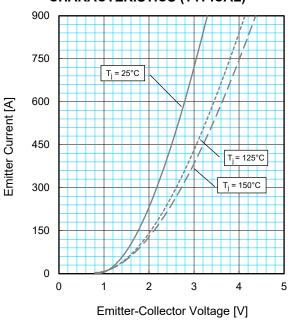
Note 6. The integration range of reverse recovery charge is from $I_{\text{E}}\text{=}0A$ to $10\% I_{\text{E}}$

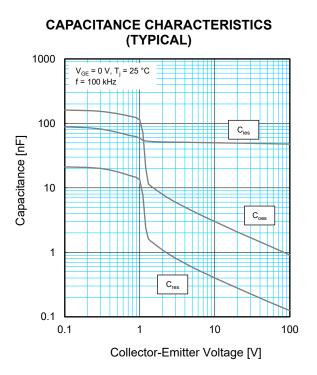


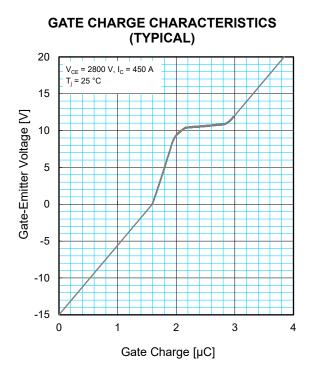




FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)

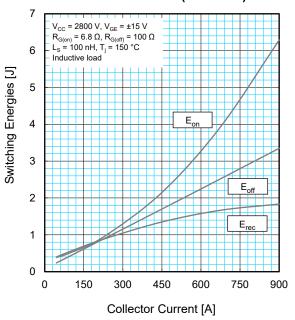






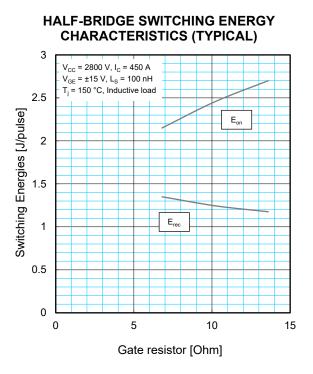
HALF-BRIDGE SWITCHING ENERGY **CHARACTERISTICS (TYPICAL)** 7 V_{CC} = 2800 V, V_{GE} = ±15 V $R_{G(on)} = 6.8 \Omega, R_{G(off)} = 100 \Omega$ L_S = 100 nH, T_j = 125 °C 6 Inductive load Switching Energies [J] 5 Eor 4 3 Eoff 2 E, 1 0 0 150 300 450 600 750 900 Collector Current [A]

HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



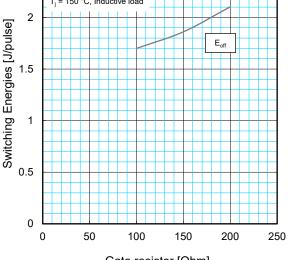
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PERFORMANCE CURVES



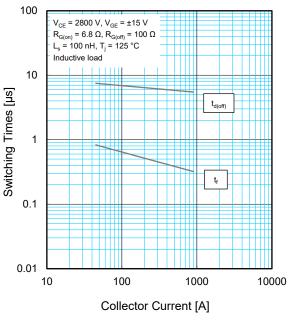
CHARACTERISTICS (TYPICAL) 2.5 $V_{cc} = 2800 \text{ V}, I_c = 450 \text{ A}$ $V_{cf} = \pm 15 \text{ V}, L_s = 100 \text{ nH}$ $T_j = 150 \text{ °C}, Inductive load$. 2

HALF-BRIDGE SWITCHING ENERGY

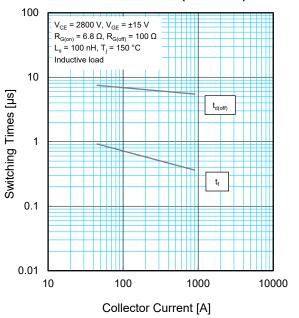


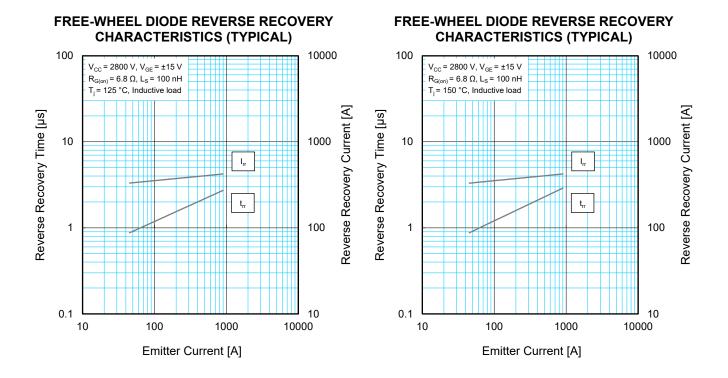
Gate resistor [Ohm]

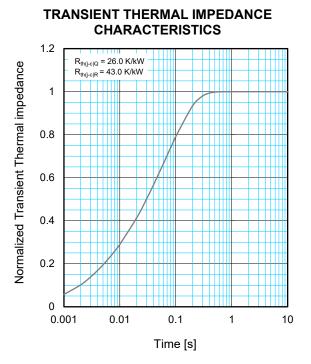
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)

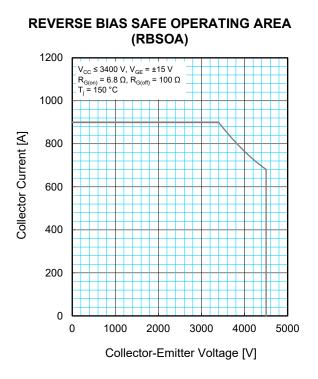




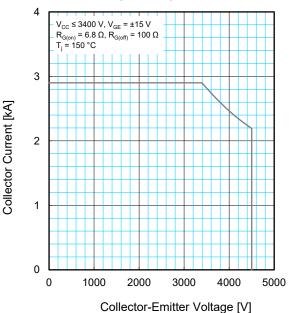


$$Z_{th(j-c)}(t) = \sum_{i=1}^{n} R_i \left\{ 1 - exp^{\left(-\frac{t}{\tau_i}\right)} \right\}$$

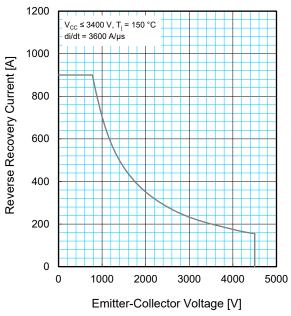
	1	2	3	4
Ri / Rth(j-c)	0.0292	0.0832	0.2277	0.6599
τ i [s]	0.0025	0.0027	0.0155	0.0865



SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)



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